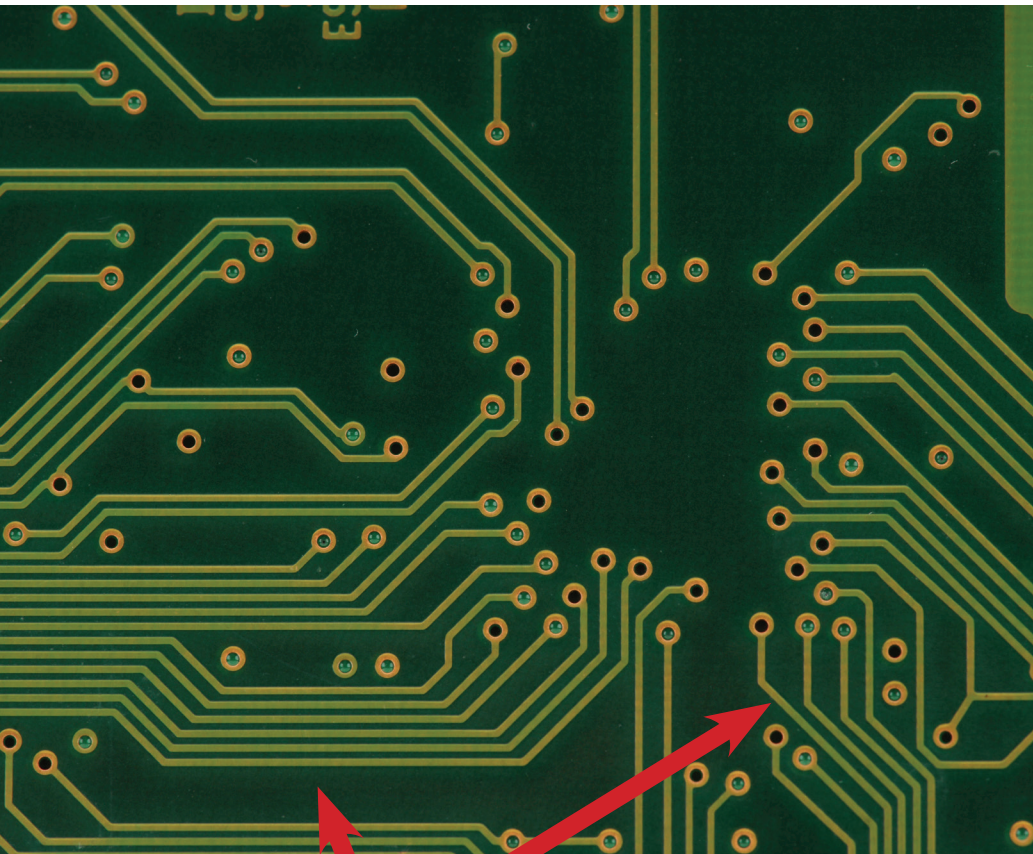




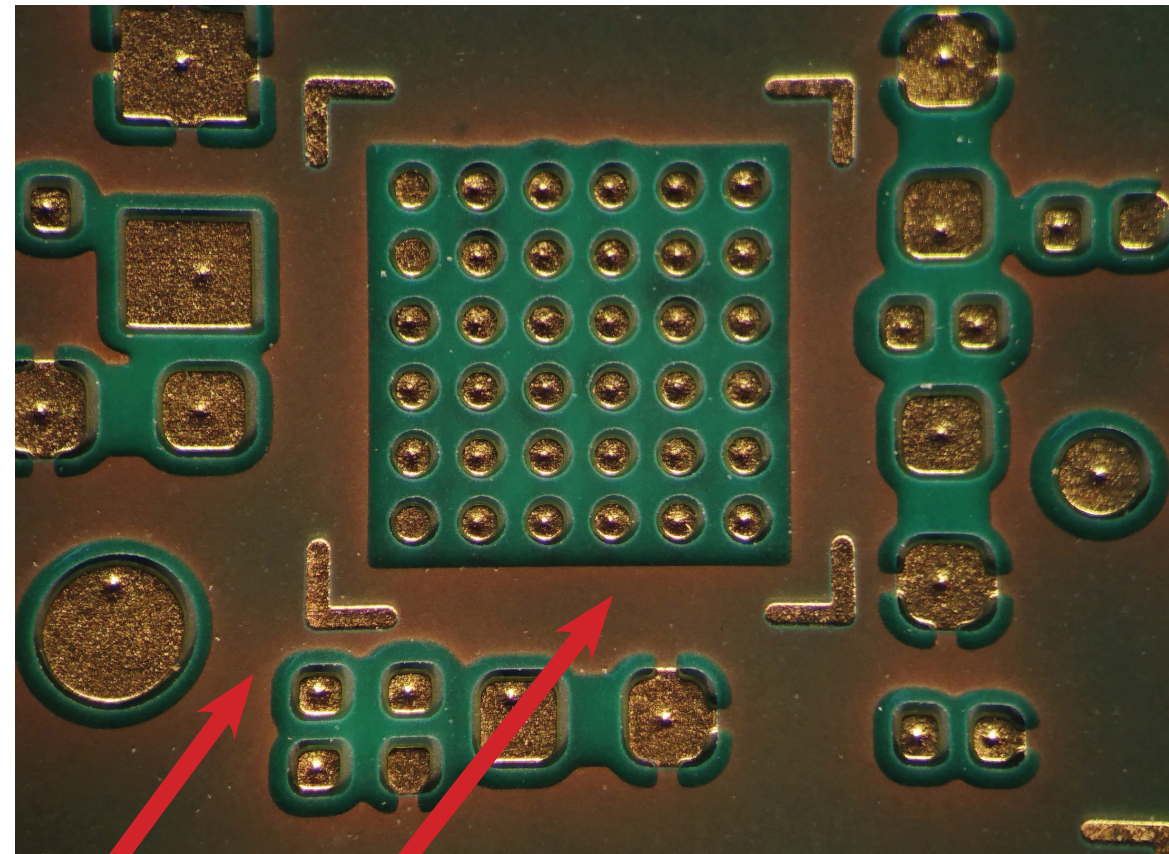
masters of microns<sup>o</sup>

**PRINTED CIRCUIT BOARDS WITH  
100% COATING CONSISTENCY**

**WHEN EVERYTHING IS CONNECTED ON INNER LAYERS, TRACKS DISAPPEAR,  
MORE ELEMENTS CAN BE FITTE ON LESS SPACE.**



**TRACKS VISIBLE**



**TRACKS NOT VISIBLE**

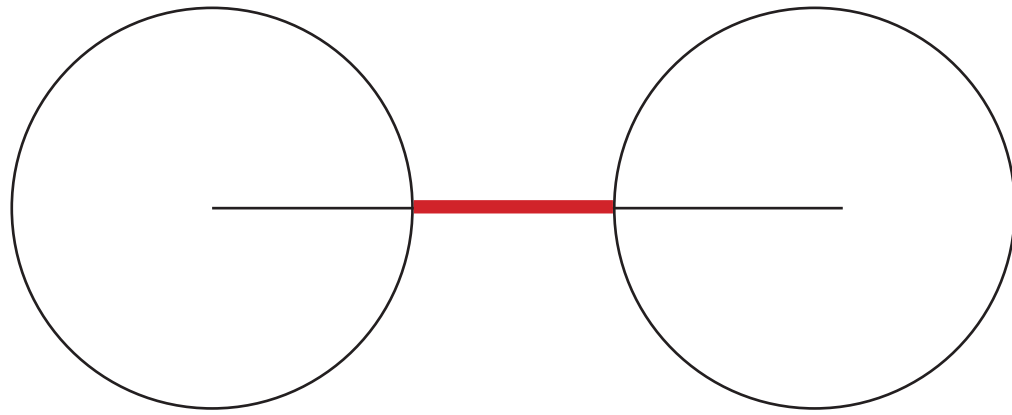




## WELL COW SYSTEM FOR TRACKING BOVINE HEALTH.

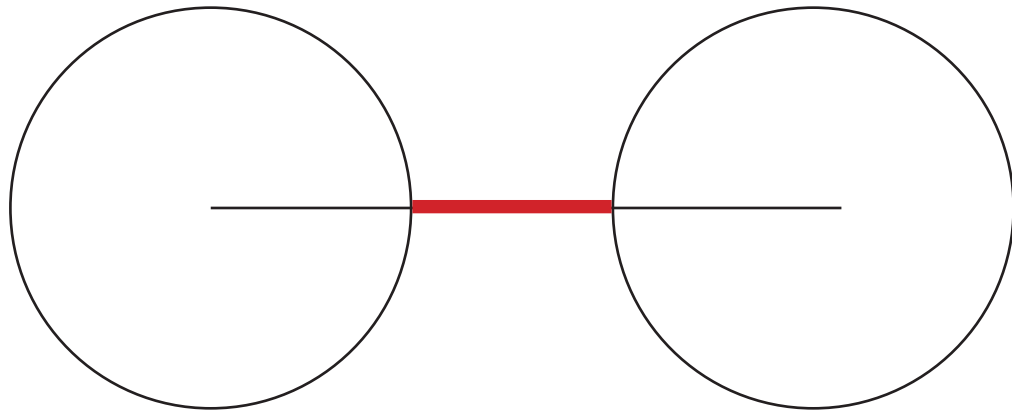
Photo by Endgaget.

# GETTING 2-3x HIGHER DENSITY THAT STANDARD AND TOOL LIMITS

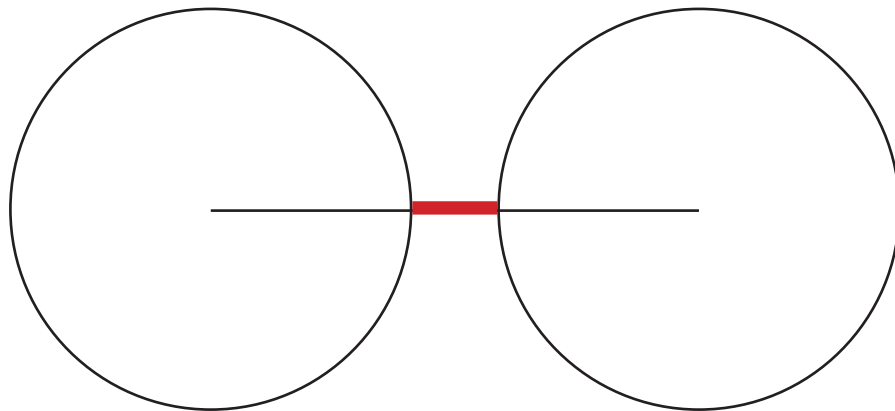


**0,5mm PITCH**

# GETTING 2-3x HIGHER DENSITY THAT STANDARD AND TOOL LIMITS

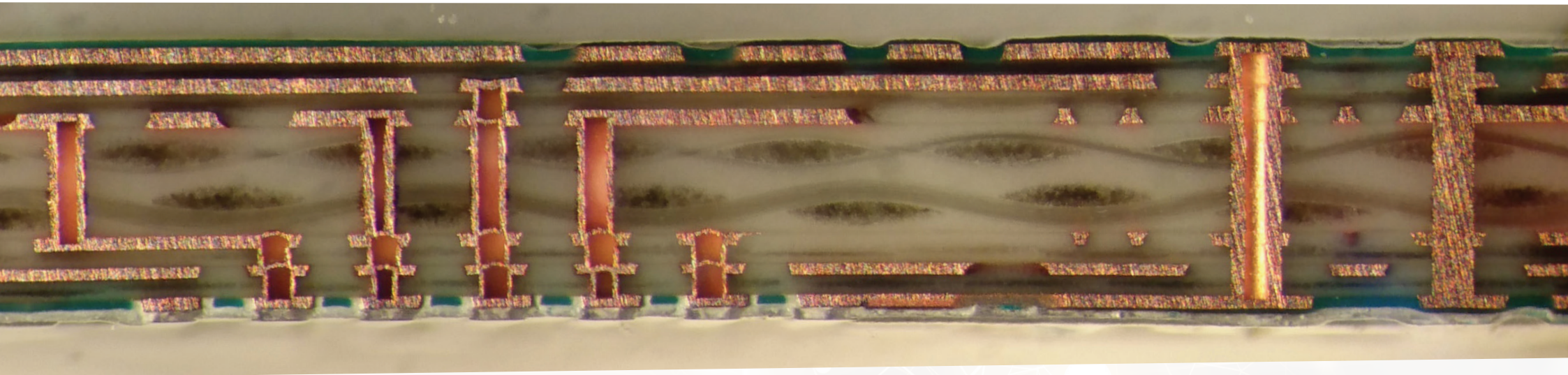


**0,5mm PITCH**

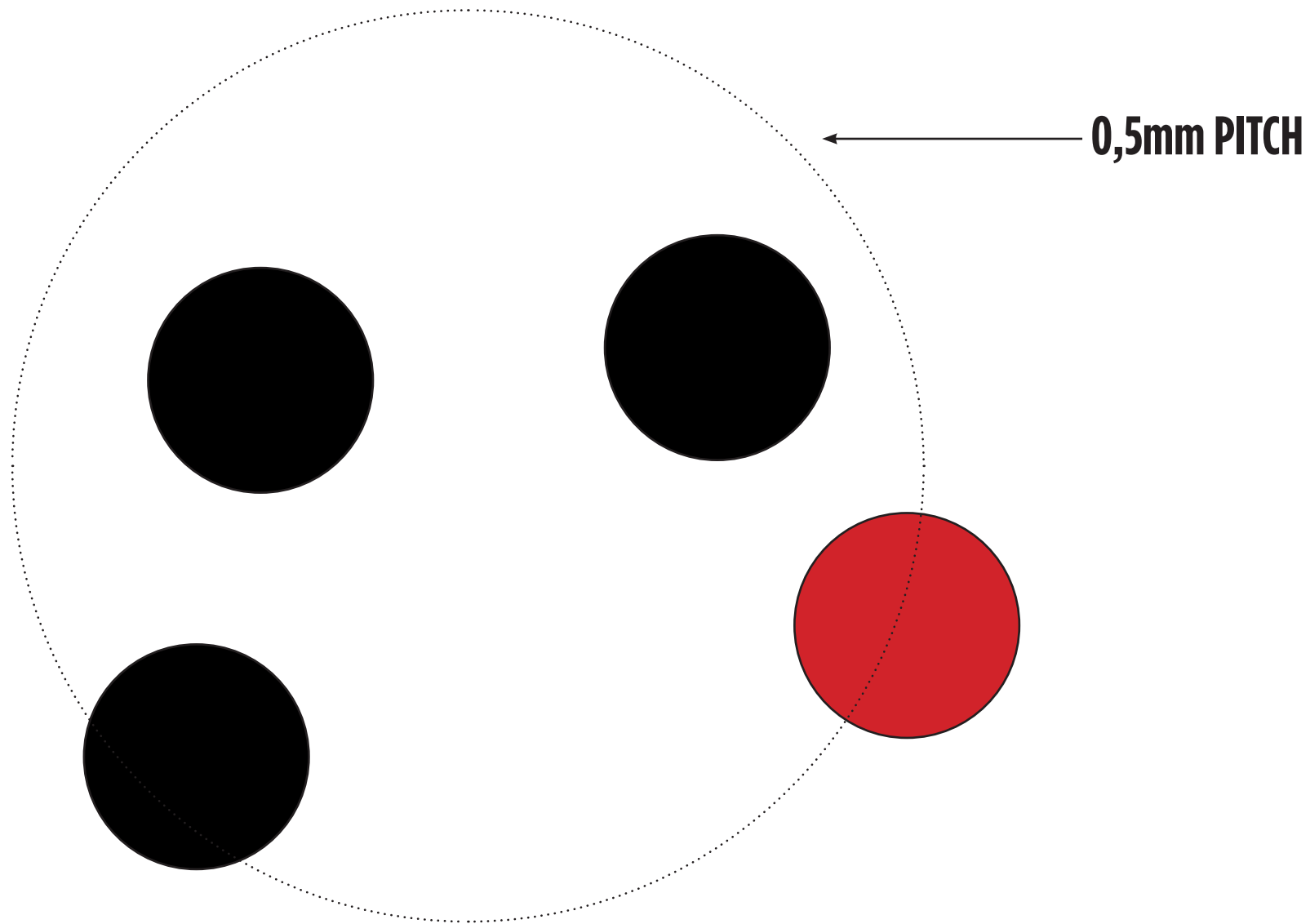


**0,2mm PITCH**

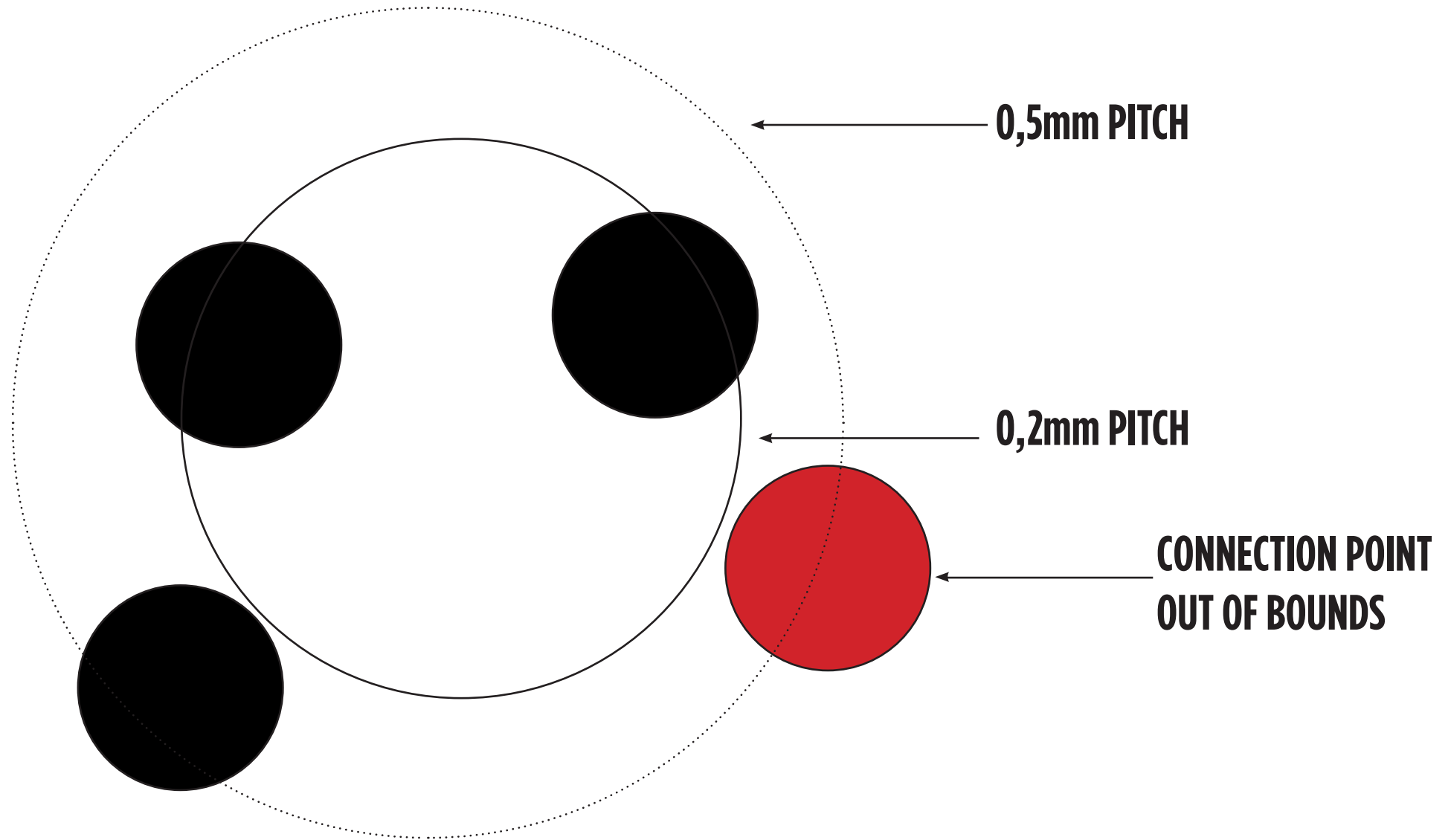
**“Today we get within 0,2 mm and stack them in 30+ layers, allowing customers to build devices 10x smaller than an average smartphone with 100x higher reliability”**



# MISS CONNECTION POINTS AND STILL COMPLY WITH STANDARD



# MISS CONNECTION POINTS AND STILL COMPLY WITH STANDARD





# INTEC 5G

3-stage printed circuit board development for device manufacturers

1

**PROTOTYPING**

2 WEEKS  
(200 STEP PROCESS)

**IMPROVED LAYOUT  
AND DESIGN**

2

**MARKET ENTRY**

6 MONTHS

**OPTIMAL MATERIAL  
SELECTION**

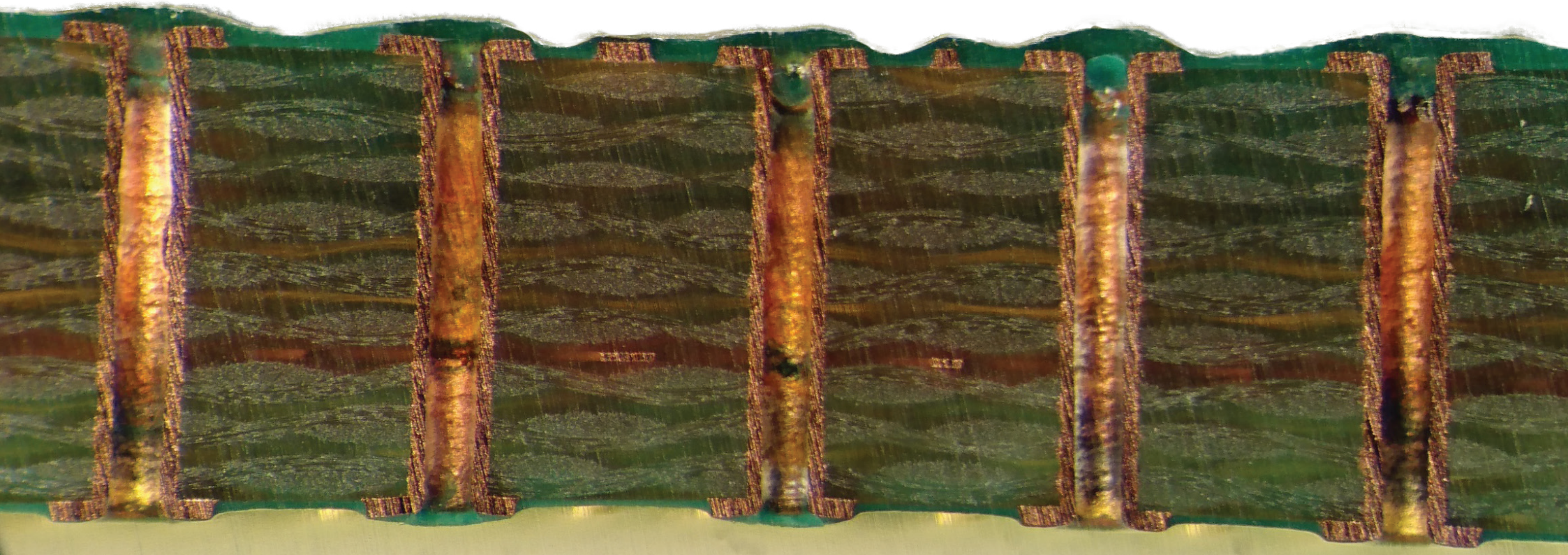
3

**SCALE UP**

2 YEARS

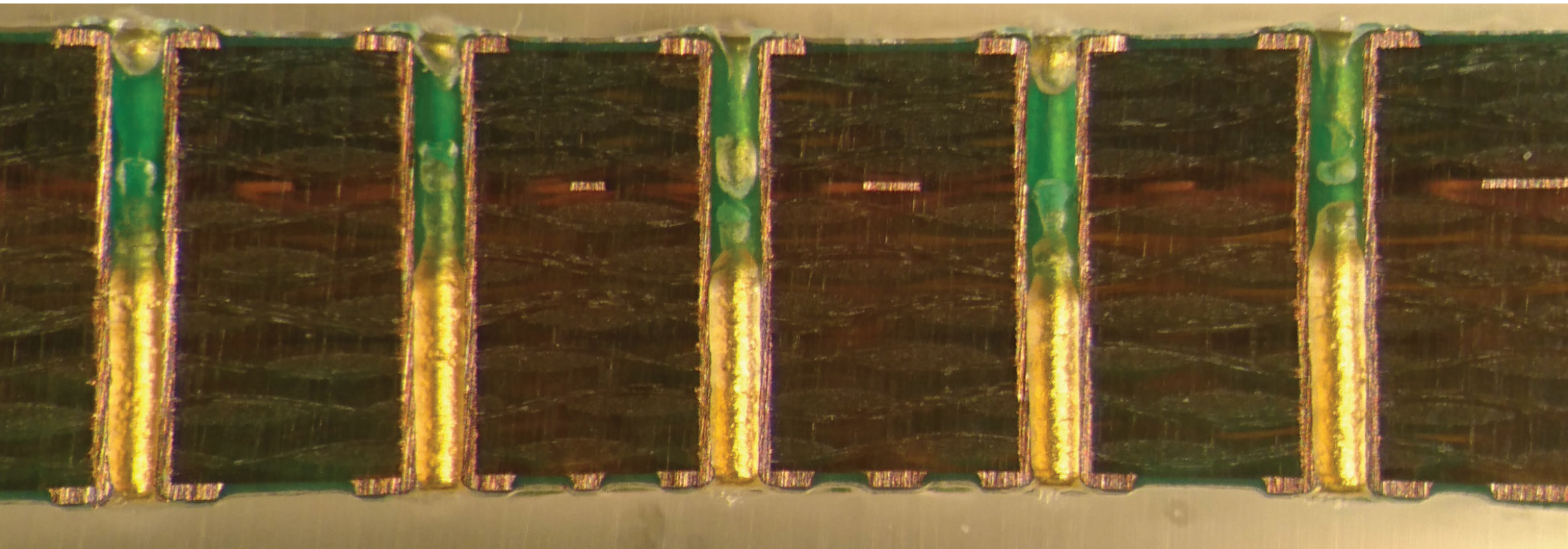
**INCREASED  
FUNCTION & RELIABILITY**

**Product finished per customer design.  
Unprotected copper surface in via holes reduce reliability.**



**INTECTIV**

**In this image, finished product made with INTEC 5G modified process flow.  
The same functionality, superior reliability.**



**INTECTIV**

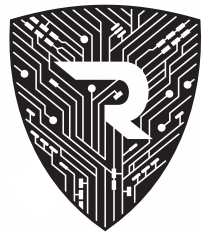
**HELPING BILLION DOLLAR COMPANIES BUILD NEXT GEN DEVICES**



**RIMAC**  
AUTOMOBILI



HELPING BILLION DOLLAR COMPANIES BUILD NEXT GEN DEVICES



**RIMAC**  
AUTOMOBILI







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**PRINTED CIRCUIT BOARDS WITH  
100% COATING CONSISTENCY**